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(12) **United States Design Patent**
Liu

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- (54) **HEADPHONE**
- (71) Applicant: **Shenzhen Jing Peng Xing Electronic Technology Co., Ltd., Shenzhen (CN)**
- (72) Inventor: **Qi Liu, Shenzhen (CN)**
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- (51) **LOC (13) Cl.** **14-01**
- (52) **U.S. Cl.**
USPC **D14/206**
- (58) **Field of Classification Search**
USPC D14/206, 226, 205; D29/112; 2/209;
381/380, 381, 374, 378, 379; 455/90.3,
455/575.1, 569.1
CPC H04R 25/00; H04R 25/02; H04R 1/105;
H04R 1/1066; H04R 1/1016; H04R
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See application file for complete search history.

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Primary Examiner — Paula Allen Greene

(57) **CLAIM**

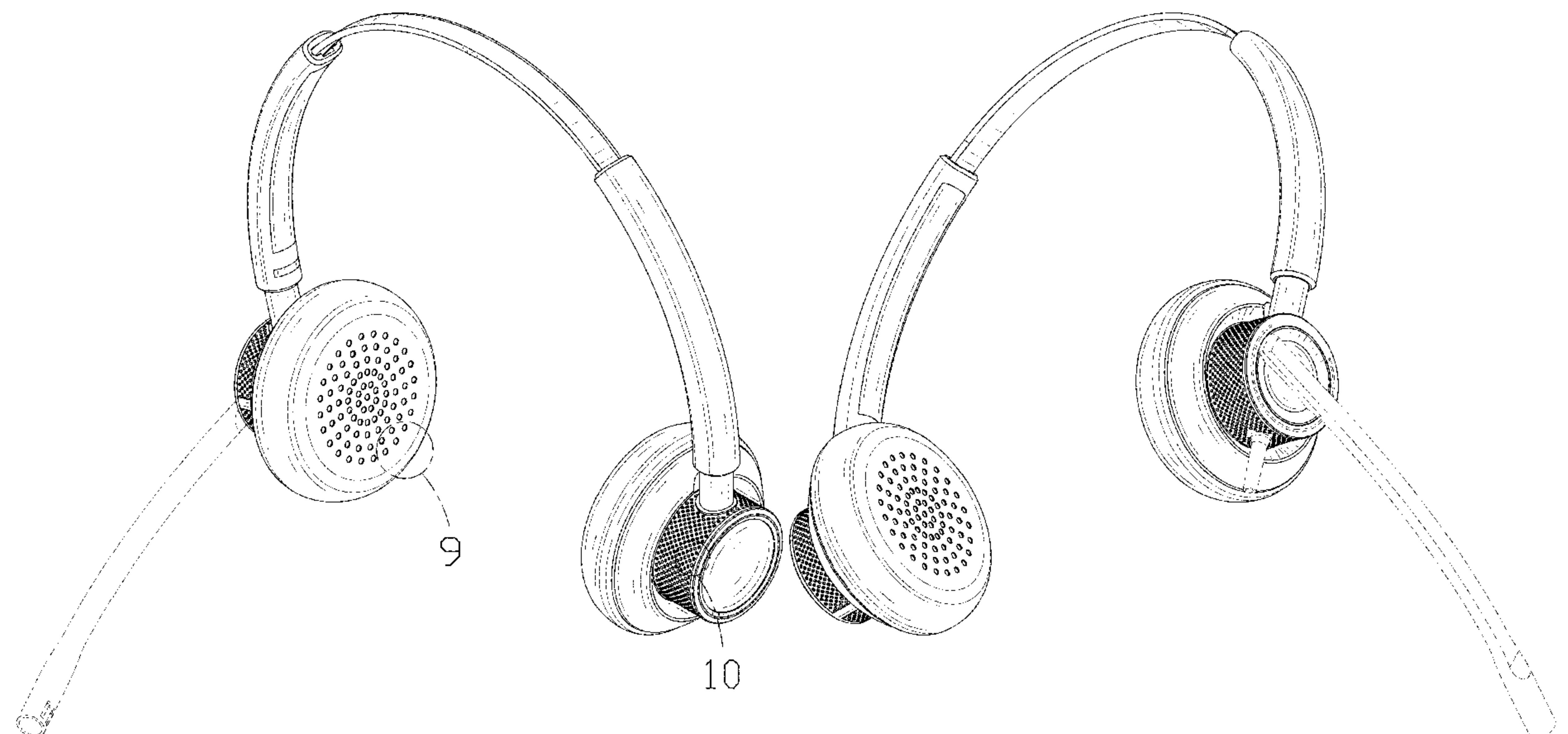
The ornamental design for a headphone, as shown and described.

DESCRIPTION

FIG. 1 is a front and top perspective view of a headphone, showing my new design;
 FIG. 2 is a rear and bottom perspective view thereof;
 FIG. 3 is a front elevation view thereof;
 FIG. 4 is a rear elevation view thereof;
 FIG. 5 is a left side elevation view thereof;
 FIG. 6 is a right side elevation view thereof;
 FIG. 7 is a top plan view thereof;
 FIG. 8 is a bottom plan view thereof;
 FIG. 9 is an enlarged view of a portion indicated with number 9 in FIG. 1; and,
 FIG. 10 is an enlarged view of a portion indicated with number 10 in FIG. 1.
 The broken lines in the figures illustrate portions of the headphone that form no part of the claimed design. The dash dot dash lines in FIGS. 1, 9 and 10 are for the purpose of depicting the cut line of the enlarged view and form no part of the claim.

1 Claim, 10 Drawing Sheets

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FIG. 1



FIG. 2



FIG. 3



FIG. 4

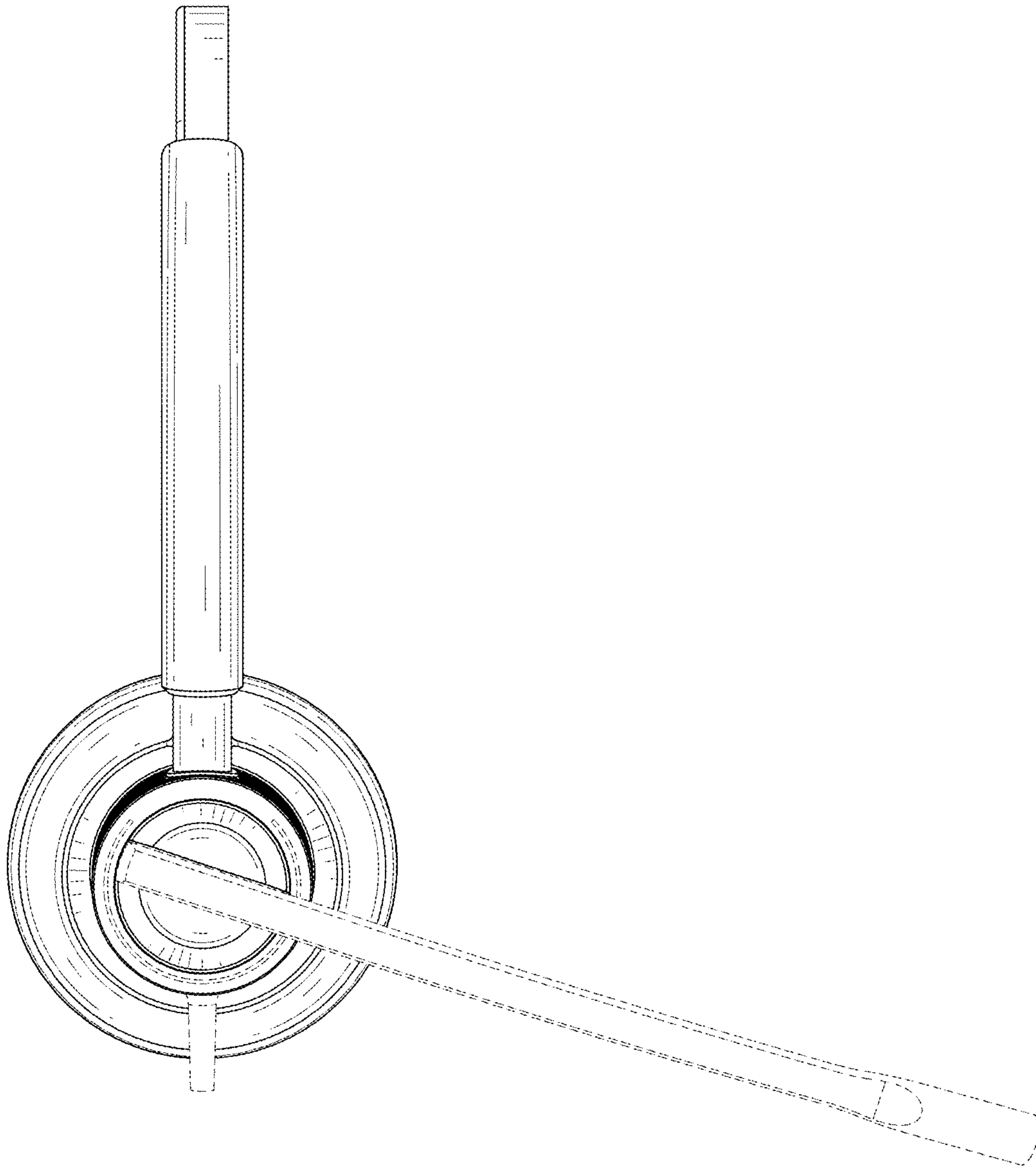


FIG. 5

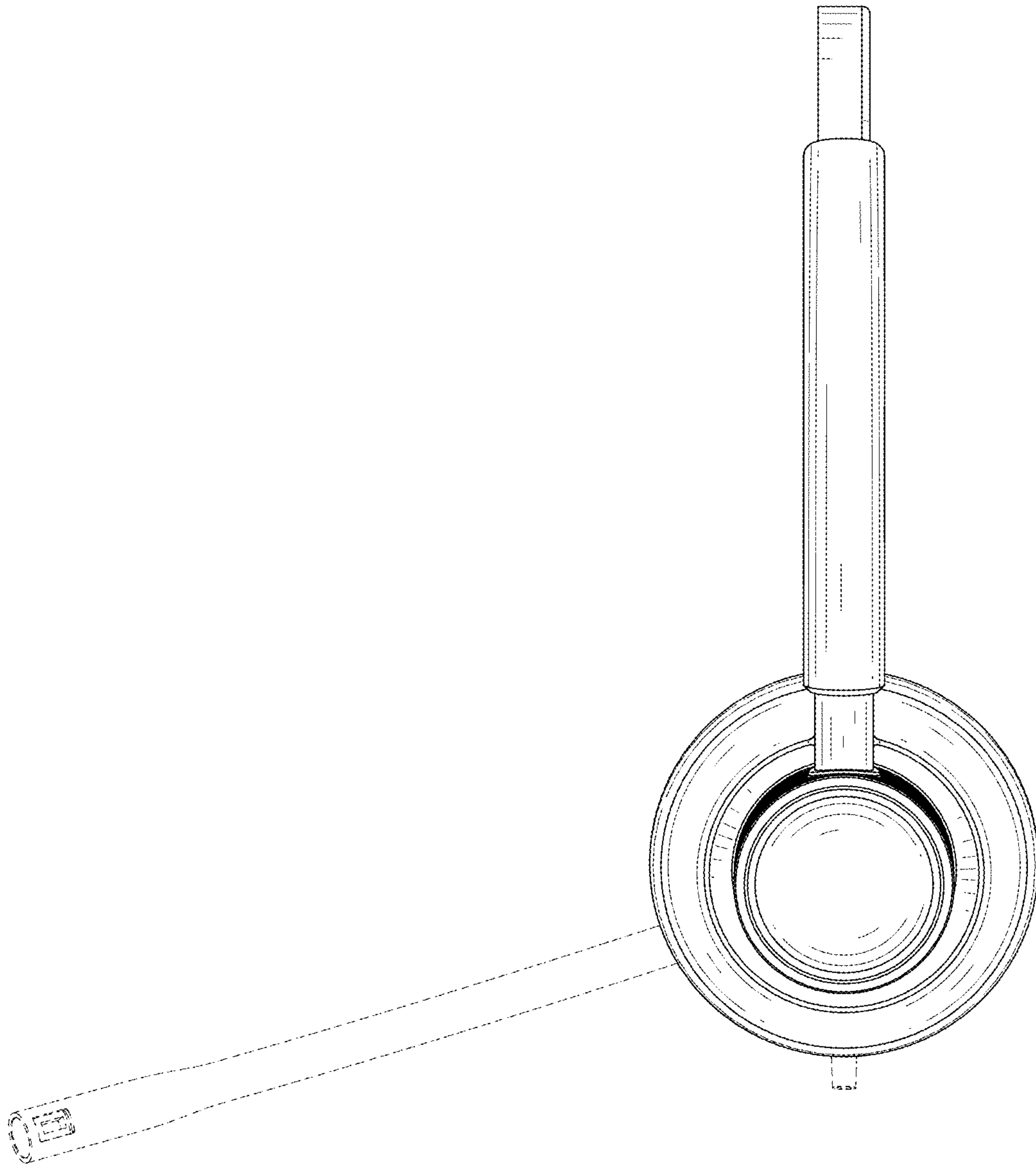


FIG. 6

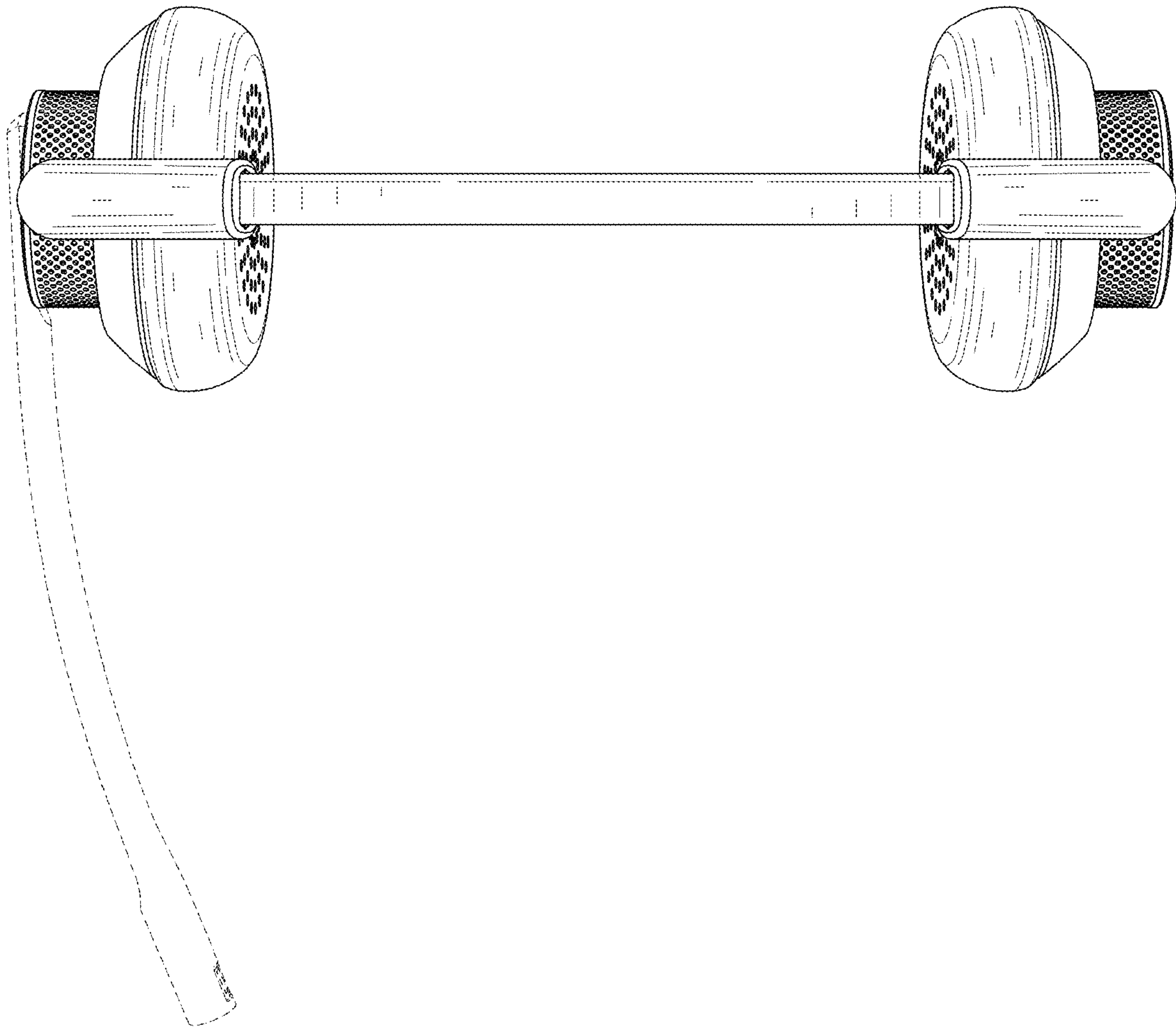


FIG. 7

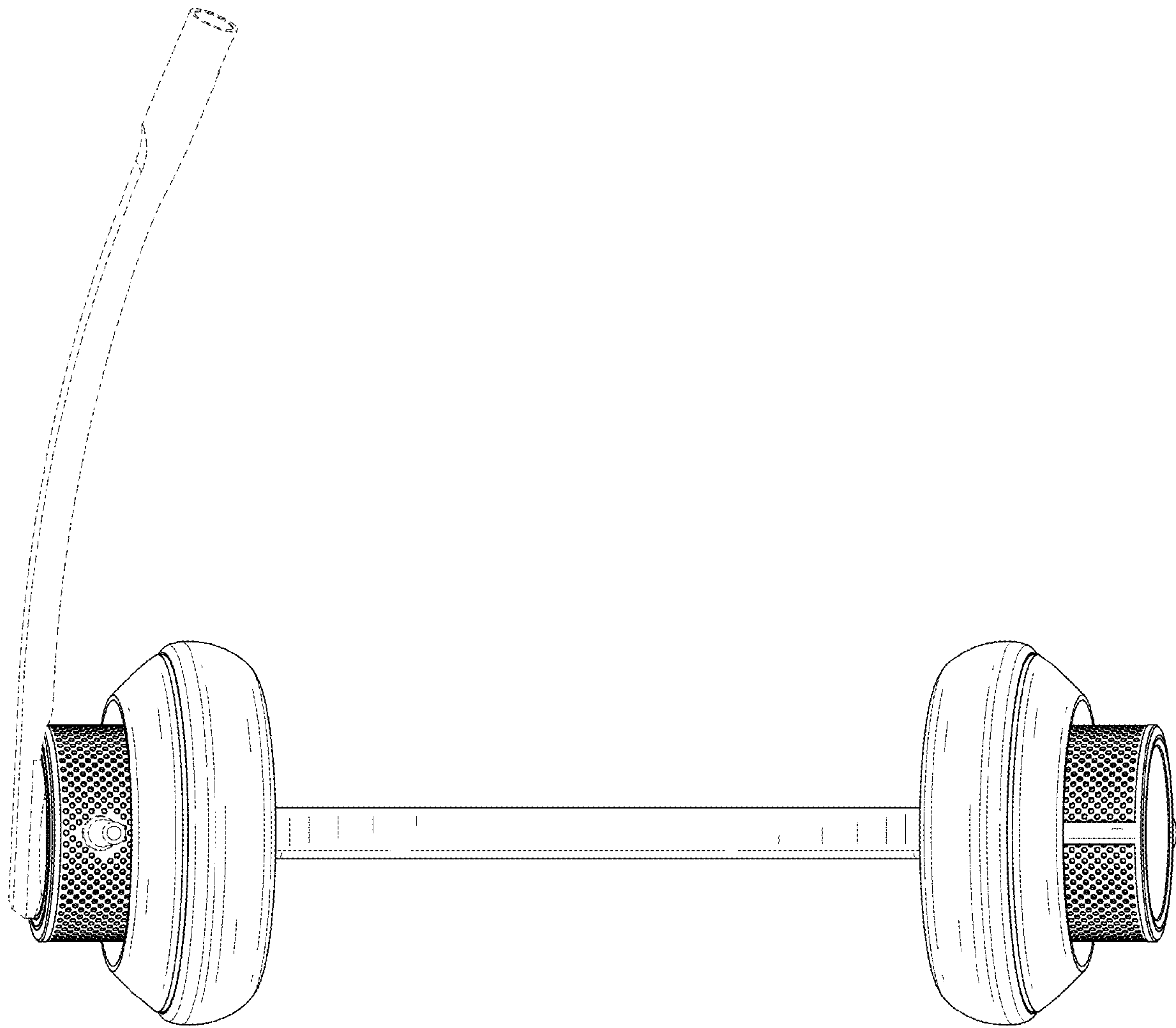


FIG. 8

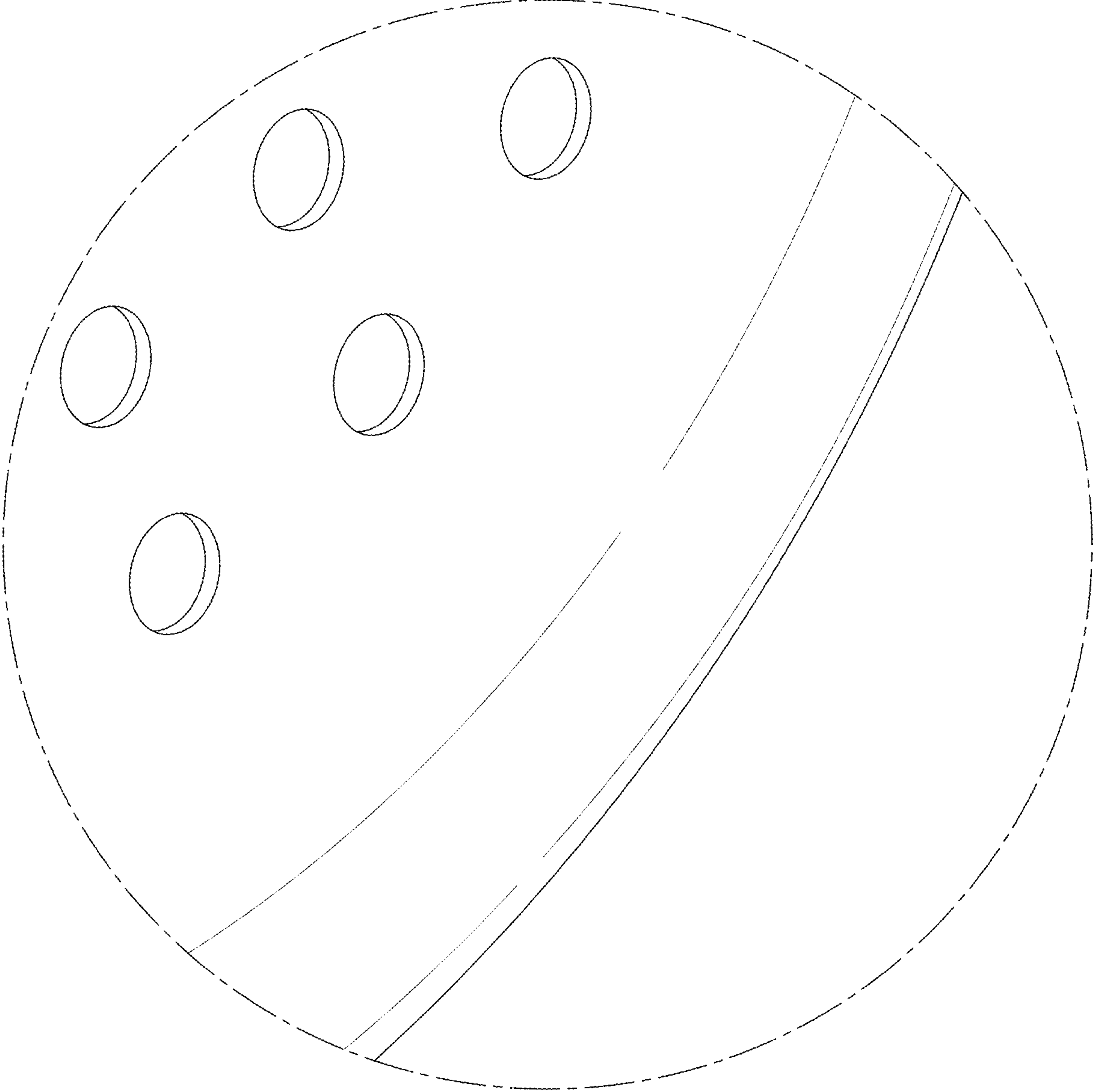


FIG. 9

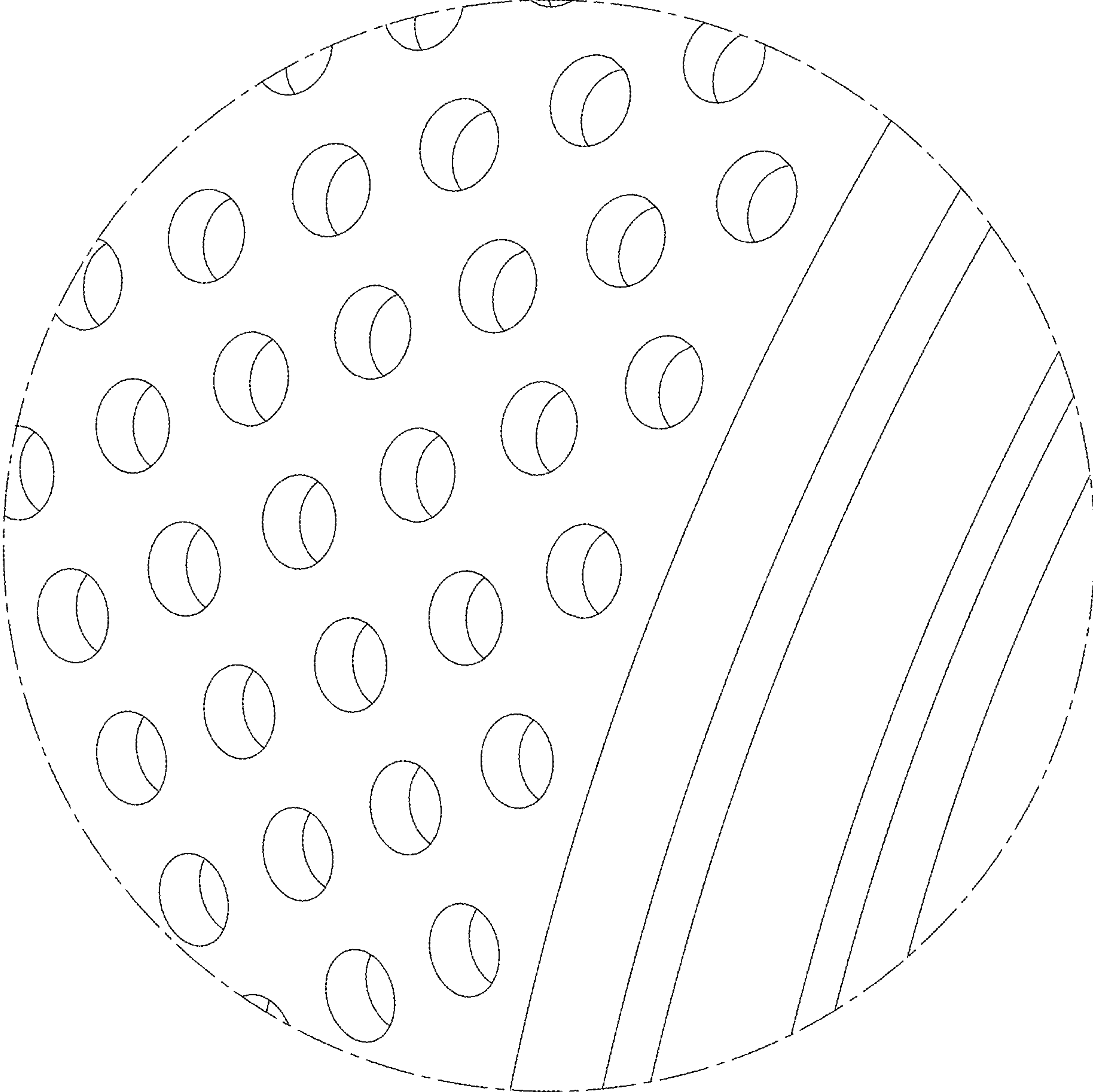


FIG. 10